

CHO-BOND® 584-29

TWO COMPONENT EASY TO USE CONDUCTIVE EPOXY ADHESIVE

Customer Value Proposition:

CHO-BOND 584-29 is a two-component, silver filled conductive epoxy adhesive system designed for applications where a strong, highly conductive electrical bond must be achieved. CHO-BOND 584-29 is recommended for relatively small bond lines (less than 0.010 inches (0.25mm)), but can be used for larger bond lines in applications where vibration or potential for cracking is not an issue. The fine silver filler of CHO-BOND 584-29 make it a good material choice for precise application in and around tight spaces and electrical components. CHO-BOND 584-29 comes in a variety of sizes and packaging so customers can choose a package and material size which is right for their application, minimizing material scrap and mixing issues.

Curing of CHO-BOND 584-29 can be achieved in as little as 15 minutes with heat to minimize equipment downtime and increase manufacturing throughput. Typical applications include bonding and grounding of electrical components, cold soldering, and bonding and sealing machined enclosures.



Features and Benefits:

- Two component
- Silver filler
- Epoxy
- Multiple packaging options
- Thin paste
- Low VOCs
- Fast heat cure, increases throughput, minimizes equipment downtime.
- Excellent conductivity 0.002 ohm-cm
- 30 minute working life, works well over wide temperature range, good chemical resistance >1200 psi lap shear, good for permanently bonding surfaces.
- No weighing required, mix and dispense in same package, minimizes process scrap.
- May be dispensed out of very small needles, fill small cracks and voids.
- Minimal shrinkage

Contact Information:

www.chomerics.com
www.hitek-ltd.co.uk
www.parker.com/chomerics

CHO-BOND® 584-29

GENERAL PROCESSING INSTRUCTIONS

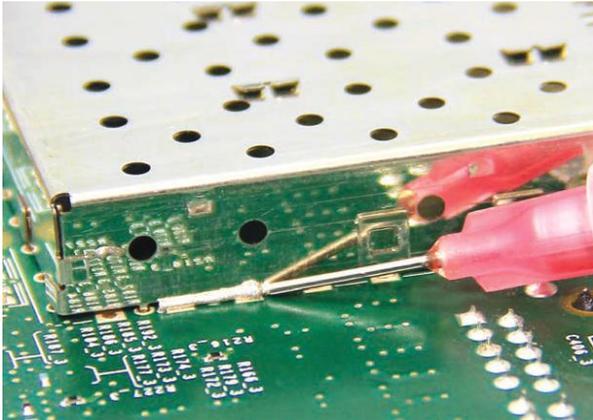
The mix proportion of self-contained CHO-PAK kits is conveniently premeasured. Simply squeeze or roll the two-chambered packet for a minute, snip off the end and apply. CHO-PAKS eliminate waste and weighing errors.

Bulk material should be thoroughly mixed with a spatula (1 to 2 minutes) at high shear. Mixed resin may then be applied to surfaces cleaned with a solvent such as trichlorethylene or toluene.

Better adhesion can be obtained with a sand blasted or chemically etched surface. CHO-BOND 584 can be applied by spatula, dispensed from a syringe with 27 (max.) ga. needle, or silk screened.

Fully cured CHO-BOND 584 adhesive exhibits a dc volume resistivity of 0.002 ohm-cm and is usable over a wide temperature range. Adhesion to copper, bronze, cold-rolled steel, aluminium, magnesium, kovar, nickel, ceramic, phenolic and plastic is excellent.

Store unmixed components in tightly closed containers in a cool place. Do not dilute CHO-BOND 584 with any solvent without prior discussion of application details with Chomerics.



When used in machined seams, CHO-BOND 584 adhesive provides an excellent EMI shield; however it should not be used for shielding lightweight, poorly toleranced enclosures. For these parts CHO-BOND 360 adhesive, a coarser system should be used. CHO-BOND 584 works well as a ground in all applications.

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CHO-BOND 584-29 - Product Information

Table 1 Typical Properties

Typical Properties	Typical Values	Test Method
Polymer	Epoxy	N/A
Filler	Silver	N/A
Mix Ratio, A : B (by weight)	100 : 6.3	N/A
Colour	Silver	N/A (Q)
Consistency	Very Thin Paste	N/A (Q)
Maximum DC Volume Resistivity (Cure Cycle 1)	0.002 ohm-cm	CHO-95-40-5101* (Q/C)
Minimum Lap Shear Strength (Cure Cycle 1)	1200 psi (8274 kPa)	CHO-95-40-5300* (Q/C)
Specific Gravity (Room Temp Cure)	2.5	ASTM D792 (Q/C)
Hardness (Cure Cycle 1)	80 Shore D	ASTM-D2240 (Q)
Continuous Use Temperature	- 55°C to 125°C (-67°F to 257°F)	N/A (Q)
Elevated Temperature Cure Cycle	Cure Cycle Option 1: 0.25 hour @ 113°C (235°F) Cure Cycle Option 2: 2.0 hours @ 65°C (150°F)	N/A
Room Temperature Cure	24 hours	N/A (Q)
Working Life	0.5 hours	N/A (Q)
Shelf Life, unopened	12 months @ 25°C (77°F)	N/A (Q)
Minimum thickness recommended	0.001 in (0.03 mm)	N/A
Maximum thickness recommended	None	N/A
Volatile Organic Content (VOC)	0 g/l	Calculated
Typical Coverage Area at 0.010" Thick per Pound (454 grams)	11,000 in ² (70,968 cm ²)	N/A

Note: N/A – Not Applicable, (Q/C) - Qualification and Conformance Test, (Q) - Qualification Test

* This test Method is available from Parker Chomerics.

Table 2 Ordering Information

Product	Weight (grams)	Packaging	Part Number	Primer Included
CHO-BOND 584-29	1.0	2 component, premeasured CHO-PAK	50-10-0584-0029	Not required
	2.5	2 component, premeasured CHO-PAK	50-02-0584-0029	Not required
	10 x 3	2 component, premeasured, 10 x 3 gram syringe kits	50-30-0584-0029	Not required
	10	2 component, premeasured CHO-PAK	50-03-0584-0029	Not required
	85	2 component, 4 fluid ounce polypropylene kit	50-00-0584-0029	Not required
	454	2 component, 8 fluid ounce polypropylene kit	50-01-0584-0029	Not required

Please refer to Parker Chomerics Surface Preparation and CHO-BOND Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.

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 ELECTRONIC MATERIALS LTD

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